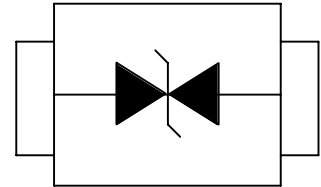


RoHS Device
Halogen Free

Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOD-323 surface mount package
- Protects bi-directional line
- Working voltage: 24V
- Low leakage current
- Low clamping voltage
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020

SOD-323



Pin Configuration

Applications

- | | |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|
| <ul style="list-style-type: none"> ● Cellular handsets & Accessories ● Cordless phones ● Personal digital assistants (PDAs) ● Notebooks & Handhelds | <ul style="list-style-type: none"> ● Portable instrumentation ● Digital cameras ● Peripherals ● MP3 players |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|

Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse power (tp=8/20μs waveform)	P _{PP}	300	W
Peak pulse current (tp=8/20μs waveform)	I _{PP}	8	A
ESD voltage (Contact discharge) ESD voltage (Air discharge)	V _{ESD}	±30	kV
Storage & operating temperature range	T _{STG} , T _J	-55~+150	°C

Electrical Characteristics ($T_J=25^{\circ}\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				24	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1\text{mA}$	26.7			V
Reverse leakage current	I_R	$V_R=24\text{V}$			0.5	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=8\text{A}$			50	V
Off state junction capacitance	C_J	$0\text{Vdc}, f=1\text{MHz}$		30		pF

Typical Characteristics Curves

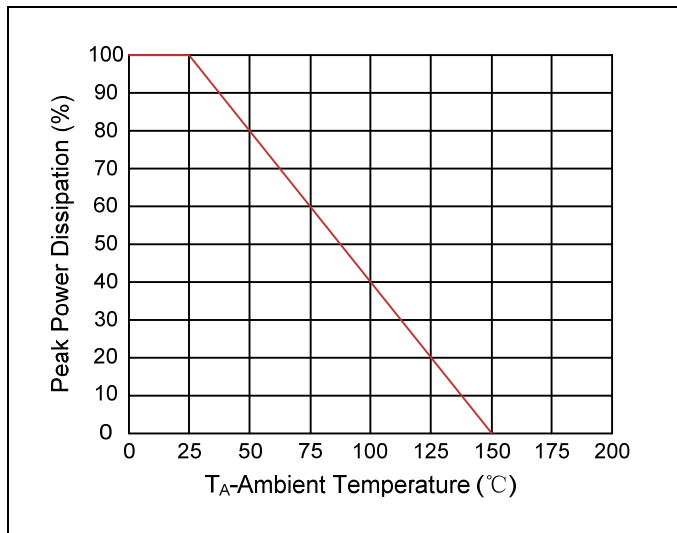


Figure 1. Power Derating Curve

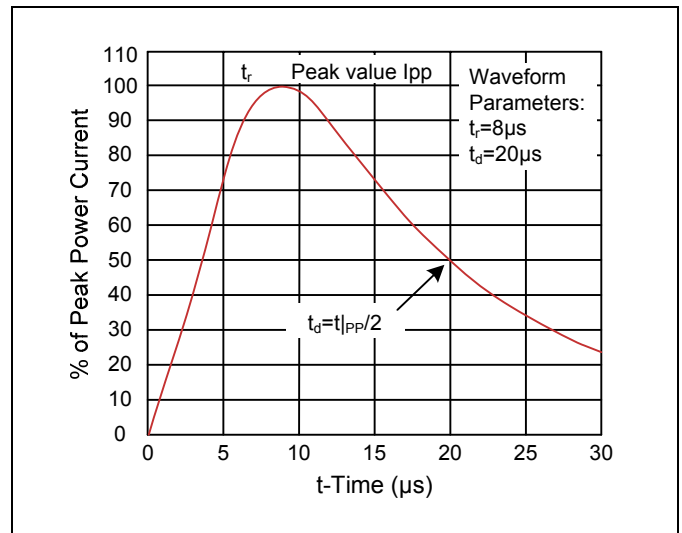


Figure 2. Pulse Waveform

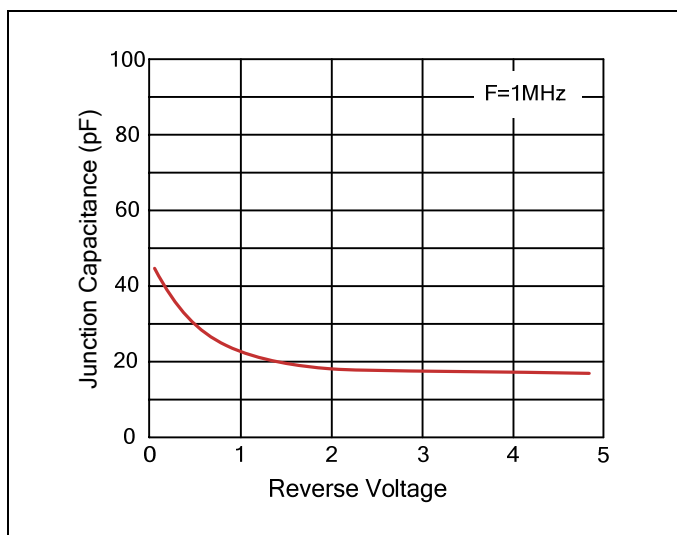
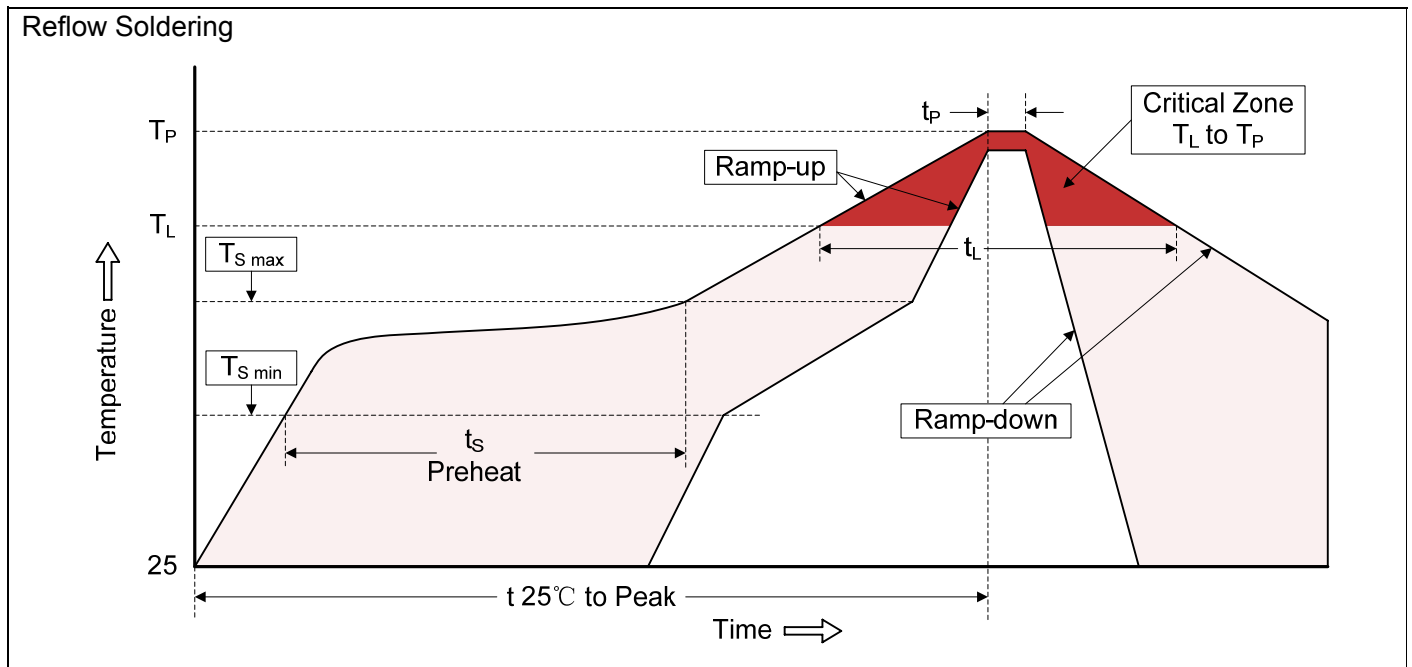


Figure 3. Capacitance vs. Reverse Voltage

Recommended Soldering Conditions



Recommended Condition

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOD-323)

<p style="text-align: center;">Recommended Soldering Pad Layout</p>	Dimension				
	Symbol	Millimeters		Inches	
		Min.	Max.	Min.	Max.
A	0.80	1.10	0.031	0.043	
B	-	0.10	-	0.004	
C	0.20	-	0.008	-	
D	0.11	0.20	0.004	0.008	
E	1.15	1.35	0.045	0.053	
F	-	0.35	-	0.014	
G	1.60	1.80	0.063	0.071	
H	2.40	2.60	0.094	0.102	

Packaging

<p>Tape</p>	Symbol	Dimension (mm)
	W	8.00±0.30
	P0	4.00±0.10
	P1	4.00±0.10
	P2	2.00±0.10
	D0	Φ1.55±0.10
	D1	Φ1.00±0.05
	E	1.75±0.10
	F	3.50±0.10
	A	1.48±0.10
	A0	0.80±0.10
	B	3.00±0.10
	B0	1.80±0.10
	K	1.05±0.10
t	0.25±0.05	

<p>Reel</p>	D	Φ178.0±2.0
	D2	Φ13.0
	W1	9.5
	Quantity: 3000PCS	